
M95512-DF package mechanical data modifications

Silicon identification

This errata sheet applies to the M95512-DF, which is 512 bit serial SPI bus EEPROMs, and specifically to the device delivered in 8-bump wafer-level chip-scale packages (WLCSP).

Table 1 shows the list of part numbers.

Table 1. Device summary

Reference	Part Number
M95512-DF	M95512-DFCS6TP/K

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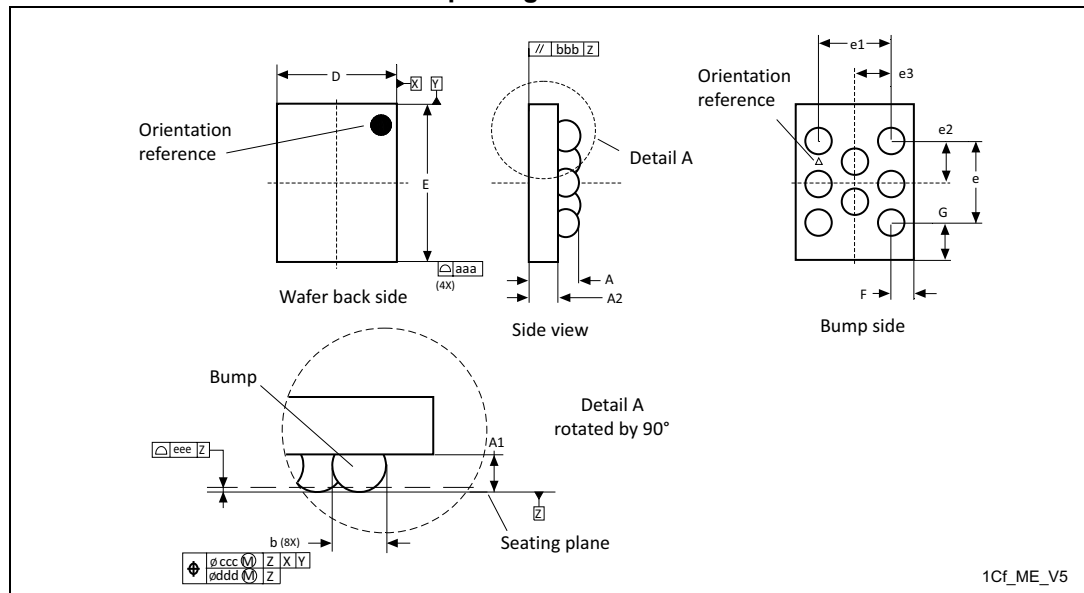
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1 M95512-DF physical product change

There is not any physical product change.

Figure 1 shows the package outline.

Figure 1. WLCSP - 8 bumps, 1.271 x 1.937 mm, 0.5 mm pitch wafer level chip scale package outline



1. Drawing is not to scale.

The figures below show the difference between D and E dimensions in the front side view (see Figure 2), back side view (see Figure 3) and side view (see Figure 4).

Figure 2. D and E front side view

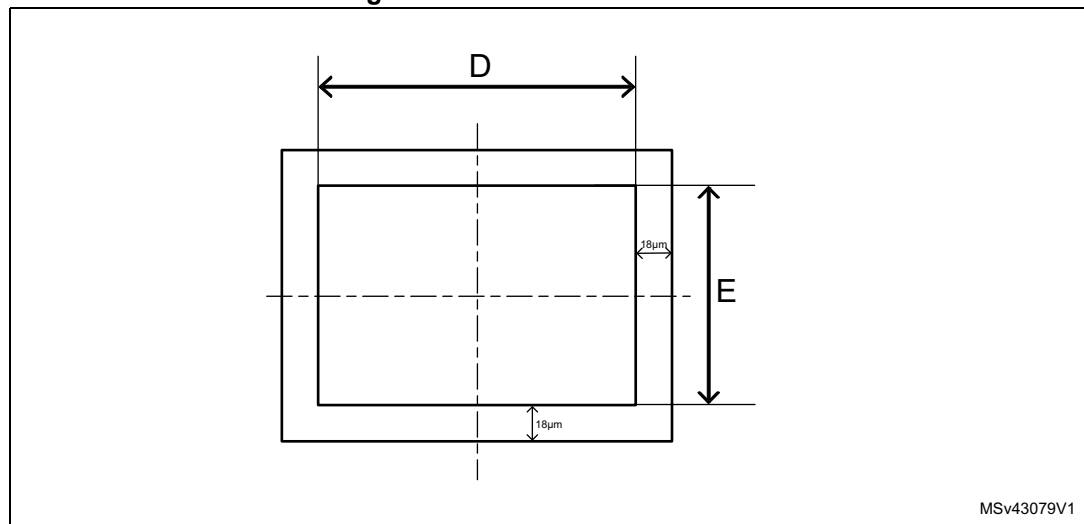


Figure 3. D and E back side view

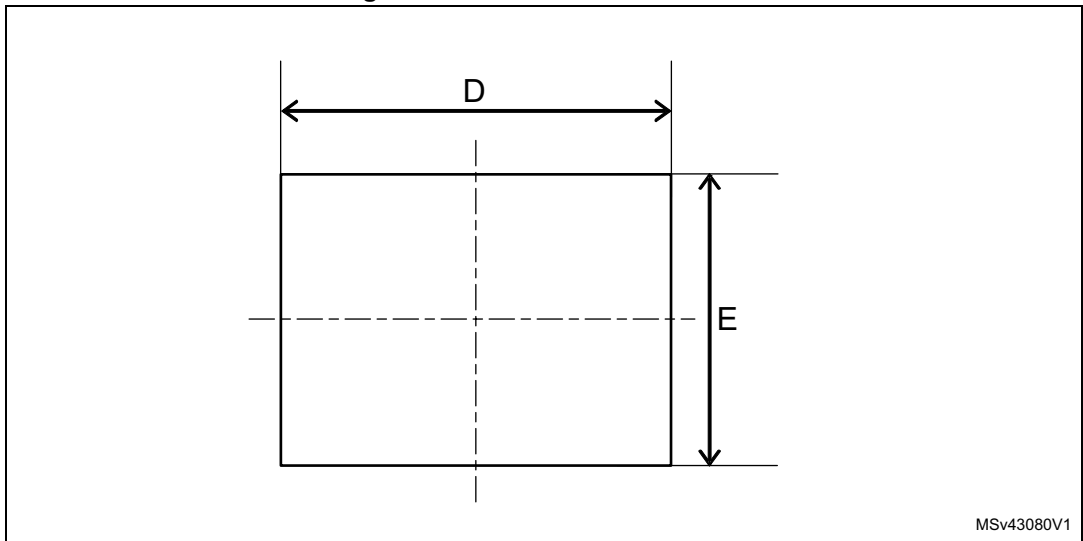
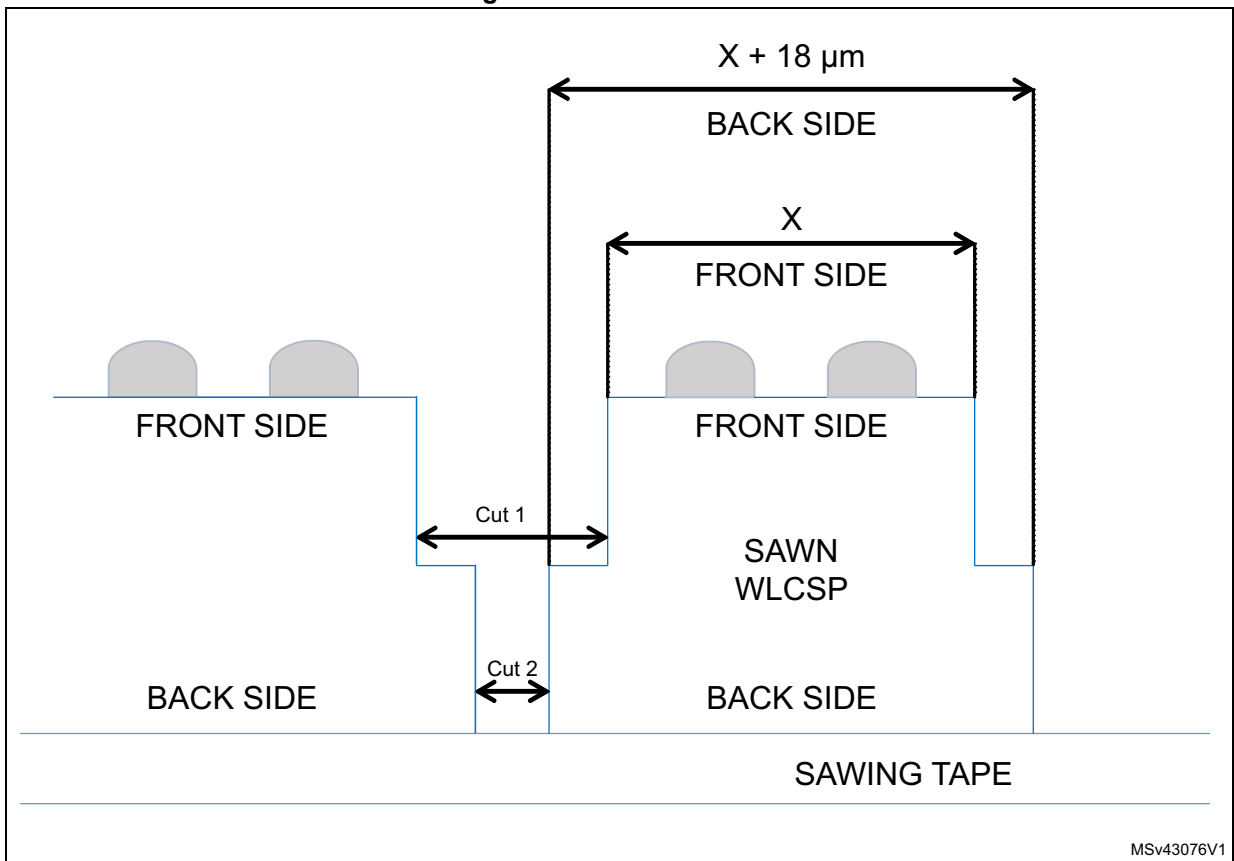


Figure 4. D or E side view



2 Package mechanical data modifications

This document refers to the changes in dimensions D and E (see [Figure 3](#)) described in the M95512-DF datasheet, in tables detailing the dimensions of the WLCSP 8-bump package.

D and E values must be modified to correct the following mistake:

- The D and E values in the M95512-DF datasheet correspond to front side view (ball side), instead of back side view (marking side view).
[Table 2](#) and [Table 3](#) report the data for the front and back view, respectively.

Table 2. D and E values corresponding to front side view

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	1.271	1.291	-	0.0500	0.0508
E	-	1.937	1.957	-	0.0763	0.0770

Table 3. D and E values corresponding to back side view

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	1.289	1.309	-	0.0507	0.0515
E	-	1.955	1.975	-	0.0770	0.0778

The difference between back side and front side dimension is 18 μm (0.018 mm). This difference is due to the two-step sawing process, where cut 1 and cut 2 are performed with blades having different thicknesses (see [Figure 4](#) in which X represents D or E and it has the same value and tolerance).

3 Revision history

Table 4. Document revision history

Date	Revision	Changes
17-Oct-2018	1	Initial release.

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